TIL187-1 THRU TIL187-4
TIL188-1 THRU TIL188-4
AC-INPUT OPTOCOUPLERS/OPTOISOLATORS

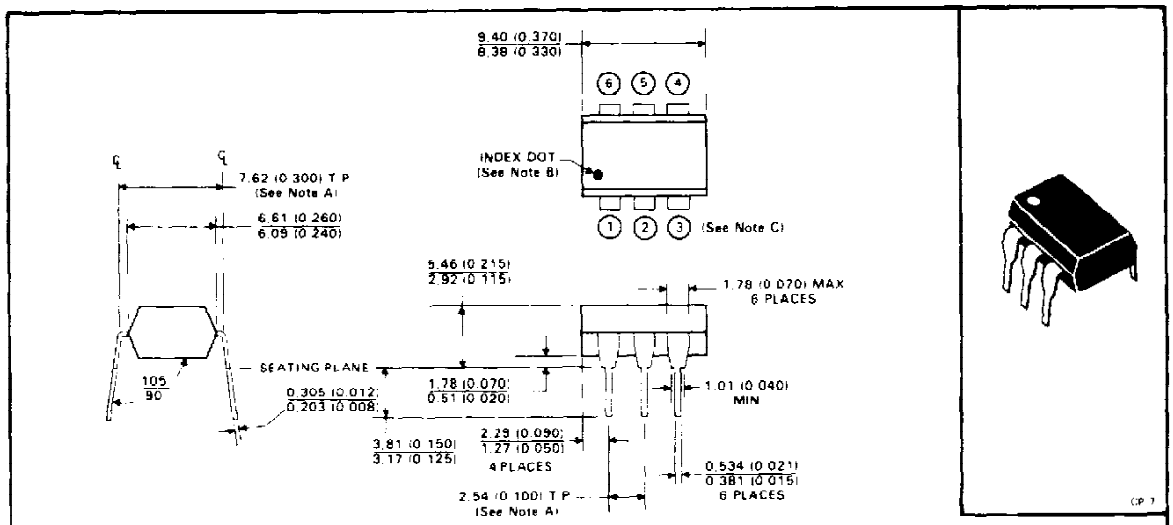
SOOS012A D2980, JANUARY 1987 – REVISED JULY 1989

- AC Signal Input
- Gallium Arsenide Dual-Diode Infrared Source Optically Coupled to a Silicon N-P-N Darlington Phototransistor
- Plastic Dual-In-Line Package
- High-Voltage Electrical Isolation, 3.535 kV Peak (2.5 kV rms)
- High Current Transfer Ratio, 500% Minimum at I_F = 10 mA, Up to 1500% Minimum at I_F = 2 mA with Four Categories
- High $V_{(BR)CEO}$, 55 V Min
- UL Recognized – File #E65085
- No Base Lead Connection on TIL188 for High-EMI Environment

description

The TIL187 and TIL188 Optocouplers are designed for use in AC applications that require very high current transfer ratio and high voltage isolation between input and output. These optocouplers consist of two GaAs light-emitting diodes connected in a reverse-parallel configuration and a silicon n-p-n Darlington phototransistor. The TIL187 has the base connected for applications where a base signal or base resistor is required. The TIL188 is designed with no base connected for applications where high base-noise immunity is desired. Users can select from four different current gains (TIL187-1 through TIL187-4 and TIL188-1 through TIL188-4).

mechanical data

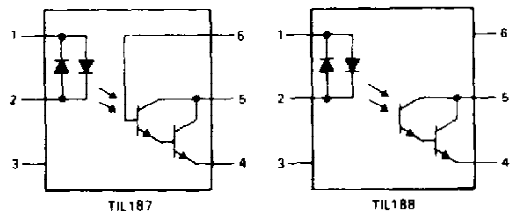


NOTES. A. Leads are within 0.13 mm (0.005 inch) radius of true position (T.P.) with maximum material condition and unit installed.

B. Pin 1 identified by index dot.

C. Terminal connections:

1. Input	}	Infrared-emitting diode
2. Input		
3. No internal connection		
4. Emitter	}	Phototransistor
5. Collector		
6. TIL187: Base		
TIL188: No internal connection		



FALLS WITHIN JEDEC MO-001AM DIMENSIONS

ALL LINEAR DIMENSIONS ARE IN MILLIMETERS AND PARENTHETICALLY IN INCHES

PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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TEXAS INSTRUMENTS
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)

Input-to-output voltage	±3.535 kV peak or dc (±2.5 kV rms)
Collector-base voltage (TIL187)	100 V
Collector-emitter voltage (see Note 1)	55 V
Emitter-collector voltage	7 V
Emitter-base voltage (TIL187)	14 V
Input diode continuous forward current at (or below) 25°C free-air temperature (see Note 2)	100 mA
Continuous power dissipation at (or below) 25°C free-air temperature:	
Infrared-emitting diode (see Note 3)	150 mW
Phototransistor (see Note 3)	150 mW
Total, infrared-emitting diode plus phototransistor (see Note 4)	250 mW
Storage temperature range	−55°C to 150°C
Lead temperature 1,6 mm (1/16-inch) from case for 10 seconds	260°C

NOTES: 1. This value applies when the base-emitter diode is open circuited.
2. Derate linearly to 100°C free-air temperature at the rate of 1.33 mA/°C.
3. Derate linearly to 100°C free-air temperature at the rate of 2 mW/°C.
4. Derate linearly to 100°C free-air temperature at the rate of 3.33 mW/°C.

electrical characteristics at 25°C free-air temperature (unless otherwise noted)

PARAMETER			TEST CONDITIONS	TIL187			TIL188			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
$V_{(BR)CBO}$	Collector-base breakdown voltage		I_C = 10 μA, I_E = 0, I_F = 0	100						V
$V_{(BR)CEO}$	Collector-emitter breakdown voltage		I_C = 1 mA, I_B = 0, I_F = 0	55			55			V
$V_{(BR)EBO}$	Emitter-base breakdown voltage		I_E = 10 μA, I_C = 0, I_F = 0	14						V
$V_{(BR)ECO}$	Emitter-collector breakdown voltage		I_E = 10 μA, I_F = 0				7			V
$I_{C(on)}$ On-state collector current	Photo-transistor operation	TIL187-1, TIL188-1	V_{CE} = 1 V, I_F = 2 mA, I_B = 0	5			5			mA
		TIL187-2, TIL188-2		10			10			
		TIL187-3, TIL188-3		20			20			
		TIL187-4, TIL188-4		30			30			
			V_{CE} = 1 V, I_F = 10 mA, I_B = 0	50			50			
	Photodiode operation		V_{CB} = 1 V, I_F = 10 mA, I_E = 0		12					μA
$I_{C(off)}$	Off-state collector current		V_{CE} = 10 V, I_F = 0, I_B = 0			100			100	nA
h_{FE}	Transistor static forward current transfer ratio		V_{CE} = 1 V, I_C = 10 mA, I_F = 0		25000					
V_F†	Input diode static forward voltage		I_F = 10 mA	1	1.2	1.5	1	1.2	1.5	V
$V_{CE(sat)}$	Collector-emitter saturation voltage		I_C = 50 mA, I_F = 10 mA, I_B = 0		0.87	1		0.87	1	V
r_{IO}	Input-to-output internal resistance		V_{in-out} = ±500 V, See Note 5	10^{11}			10^{11}			Ω
C_{io}	Input-to-output capacitance		V_{in-out} = 0, f = 1 mHz, See Note 5		1	1.3		1	1.3	pF
$\frac{I_{C(on)1}}{I_{C(on)2}}$	On-state collector current symmetry ratio (see Note 6)		V_{CE} = 1 V, I_F = 2 mA	1		3	1		3	

†These parameters apply for either direction of the input current.

NOTES: 5. These parameters are measured between both input-diode leads shorted together and all the phototransistor leads shorted together.

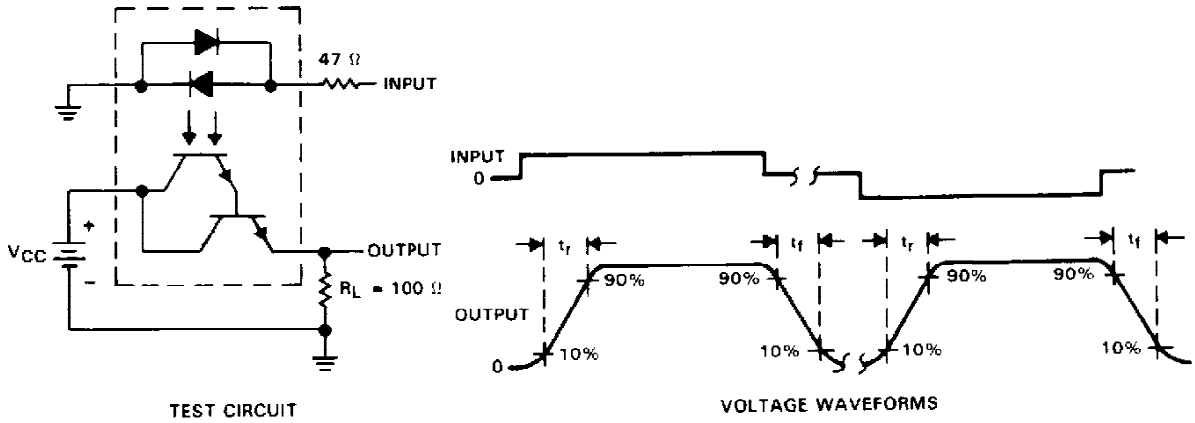
6. The higher of the two $I_{C(on)}$ values generated by the two diodes is taken as $I_{C(on)1}$.

switching characteristics at 25°C free-air temperature

PARAMETER		TEST CONDITIONS		TIL187			TIL188			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
t_r	Rise time	V_{CC} = 10 V,	$I_{C(on)}$ = 10 mA,		100			100		μs
t_f	Fall time	R_L = 100 Ω,	see Figure 1		100			100		μs

PARAMETER MEASUREMENT INFORMATION

Adjust amplitude of input pulse is for $I_{C(on)}$ = 10 mA



TEST CIRCUIT

VOLTAGE WAVEFORMS

NOTES: A. The input waveform is supplied by a generator with the following characteristics: Z_O = 50 Ω, t_r ≤ 15 ns, duty cycle = 1%.
B. The output waveform is monitored on an oscilloscope with the following characteristics: t_r ≤ 12 ns, R_I ≥ 1 MΩ, C_I ≤ 20 pF.

FIGURE 1. SWITCHING TIMES

TYPICAL CHARACTERISTICS

INPUT CURRENT
vs
INPUT VOLTAGE

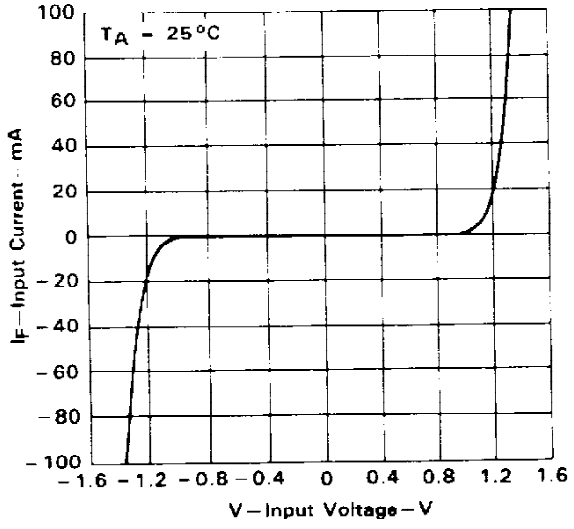


FIGURE 2

COLLECTOR CURRENT
vs
COLLECTOR-EMITTER VOLTAGE

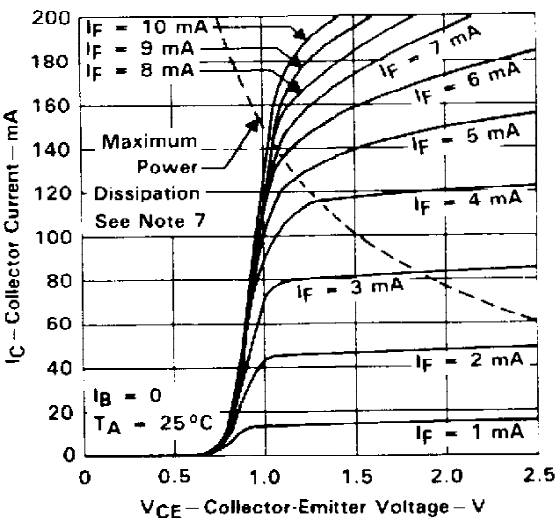


FIGURE 3

Note 7: Pulse operation is required for operation beyond limits shown by the dashed line.

COLLECTOR CURRENT
vs
INPUT DIODE FORWARD CURRENT

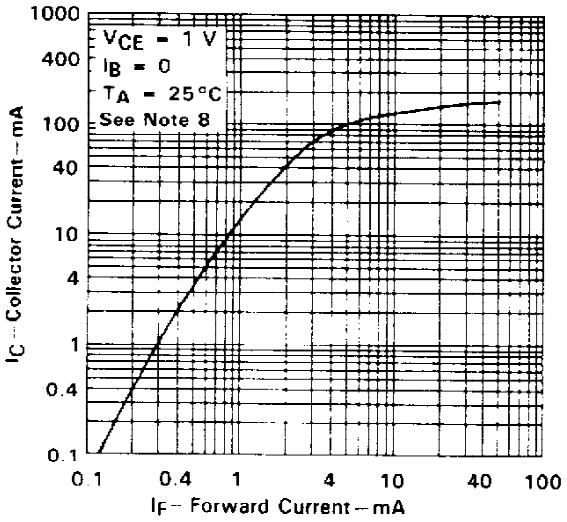


FIGURE 4

NORMALIZED ON STATE COLLECTOR CURRENT
vs
FREE-AIR TEMPERATURE

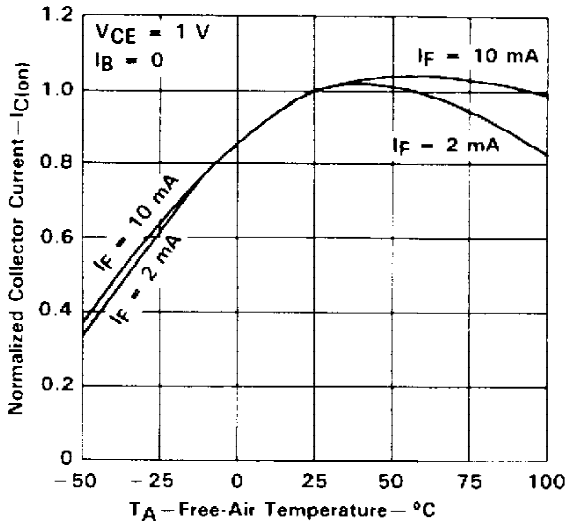


FIGURE 5

TIL187
NORMALIZED TRANSISTOR STATIC
FORWARD CURRENT TRANSFER RATIO
vs
COLLECTOR CURRENT

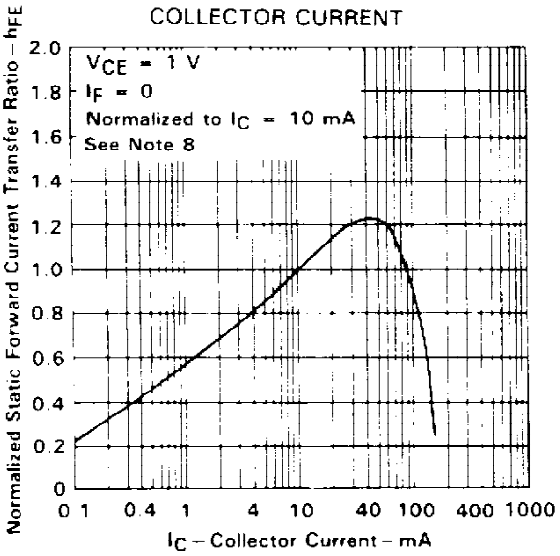


FIGURE 6

TIL187
NORMALIZED TRANSISTOR STATIC
FORWARD CURRENT TRANSFER RATIO
vs
FREE-AIR TEMPERATURE

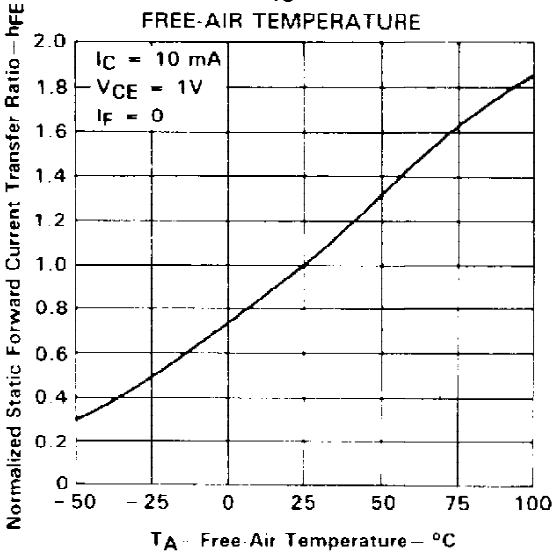


FIGURE 7

NOTE 8: These parameters were measured using pulse techniques t_w = 1 ms, duty cycle ≤ 2%.

TIL187

NORMALIZED ON-STATE COLLECTOR CURRENT
(PHOTODIODE OPERATION)
vs
FREE-AIR TEMPERATURE

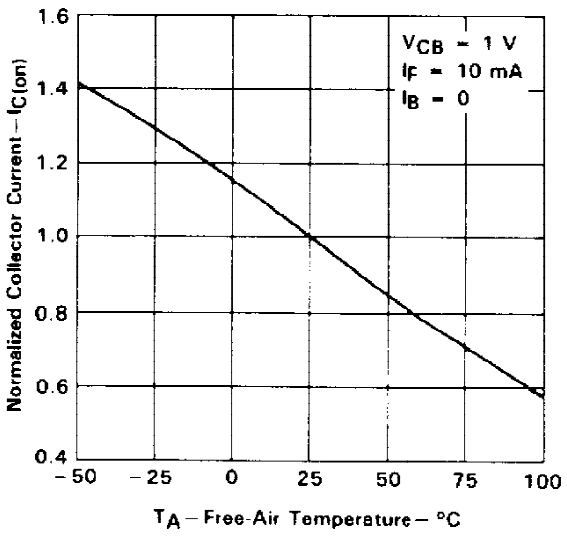


FIGURE 8

NORMALIZED COLLECTOR-EMITTER
BREAKDOWN VOLTAGE
vs
FREE-AIR TEMPERATURE

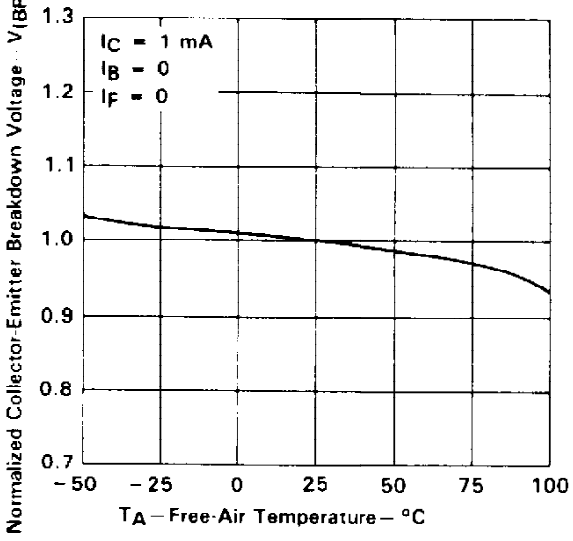


FIGURE 9

OFF-STATE COLLECTOR CURRENT
vs
FREE-AIR TEMPERATURE

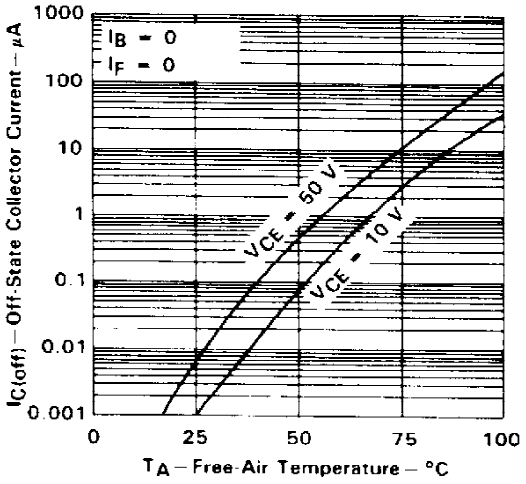


FIGURE 10

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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
TIL187-1	OBSOLETE	PDIP	N	6		TBD	Call TI	Call TI
TIL187-2	OBSOLETE	PDIP	N	6		TBD	Call TI	Call TI
TIL187-3	OBSOLETE	PDIP	N	6		TBD	Call TI	Call TI
TIL187-4	OBSOLETE	PDIP	N	6		TBD	Call TI	Call TI
TIL188-1	OBSOLETE	PDIP	P	6		TBD	Call TI	Call TI
TIL188-2	OBSOLETE	PDIP	P	6		TBD	Call TI	Call TI
TIL188-3	OBSOLETE	PDIP	N	6		TBD	Call TI	Call TI
TIL188-4	OBSOLETE	PDIP	N	6		TBD	Call TI	Call TI

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OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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